imall

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GSID100A120T2P2 IGBT PIM Module



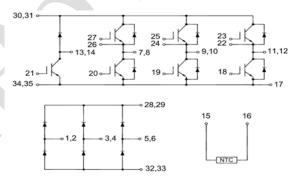
Features:

- Short Circuit Rated 10µs
- Low Saturation Voltage: $V_{CE (sat)}$ = 1.90V @ I_C = 100A ,T_C=25 °C
- Low Switching Loss
- 100% RBSOA Tested (2×Ic)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

Applications:

- Industrial Inverters
- Servo Applications





IGBT, Inverter Maximum Rated Values (T_c=25°CUnless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
		Т _С = 80°С	100	А
lc	Continuous Collector Current	T _C = 25°C	200	А
Ісм	Repetitive Peak Collector Current	TJ = 175℃	200	А
tsc	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per IGBT	T _C = 25℃ T _{Jmax} =175℃	710	W



Electrical Characteristics of IGBT (T_C =25 °C Unless otherwise specified)

Static characteristics

Symbol	Description	Conditions		Min	Тур	Max	Unit
$V_{\text{GE}(\text{th})}$	Gate-Emitter Threshold Voltage	I_{C} = 1 mA, V_{CE}	= V _{GE}	5.0	5.5	6.0	V
N	Collector Emitter Seturation Voltage	$I_{\rm C} = 100 \text{ A},$	T _J = 25℃		1.90	2.10	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage		T _J = 125℃		2.20		V
I _{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0V,$ $V_{CE} = V_{CES}, T$	V _{GE} = 0V, V _{CE} = V _{CES} , T _J = 25℃			1	mA
I _{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20V,$ $V_{CE} = 0V, T_J =$	= 25 °C		K	100	nA
C _{ies}	Input Capacitance	V_{CE} = 25V, V_{GE} = 0V , f =1MHz			13.7		nF
C _{oes}	Output Capacitance				0.78		nF

Switching Characteristics

	onuluotonotioo						
+	Turn-on Delay Time		T _J = 25℃		245	20	
t _{d(on)}			T _J = 125℃		225	ns	,
	Rise Time		T _J = 25℃		145		
t _r	Rise Time		T _J = 125℃		145	ns	,
+	Turn-off Delay Time		T _J = 25℃		420	20	
t _{d(off)}	Vcc	$V_{1} = 600V_{1} = 100A$	T _J = 125℃		450	ns	,
+ r	Fall Time	$V_{CC} = 600V, I_C = 100A,$ $R_G = 15 \Omega, V_{GE} = \pm 15V,$ Inductive Load	T _J = 25℃		170	20	
t _f	Fail Time		T _J = 125℃		230	ns	•
F	Turn on Switching Loop		T _J = 25℃		9.1		
Eon	Turn-on Switching Loss		T _J = 125℃		11.7	— mJ	,
_	Turn off Switching Loop		T _J = 25℃		5.5		
E _{off}	Turn-off Switching Loss		T _J = 125℃		7.9	— mJ	,
Qg	Total Gate Charge		T _J = 25℃		945	nC	;
RBSOA	Reverse Bias Safe Operation Area	I_{C} =200A,V _{CC} =960V,Vp=12 Rg = 15 Ω , V _{GE} =+15V to 0			Trapezoid		
SCSOA	Short Circuit Safe Operation Area	V _{CC} = 600V, V _{GE} = 15V, T _J = 150°C		10		μs	\$
R _{θJC}	IGBT Thermal Resistance: Junction-To-Case				0.21	°C/V	N



Diode, Inverter

Maximum Rated Values (T_C=25°C Unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
IF	Diode Continuous Forward Current	100	А
I _{FM}	Diode Maximum Forward Current	200	А

Electrical Characteristics of FWD (T_c=25 $^{\circ}$ C Unless otherwise specified)

Symbol	Description	Conditio	ns	Min	Тур	Max	Unit
V _{FM}	Forward Voltage	I _F = 100 A ,	T _J = 25℃		2.20	2.50	V
V FM	Forward voltage	V _{GE} = 0V	T _J = 125℃		2.40		V
1	Peak Reverse Recovery Current		T _J = 25℃		40		А
I _{rr}	Teak Neverse Necovery Current		T _J = 125℃		55		~
Q _{rr}		l _F =100A, di/dt =660A/μs,	T _J = 25℃		4.7		μC
Qrr	Reverse Recovery Charge	V _{rr} = 600V, V _{GE} = -15V	T _J = 125℃		10.6		μο
E _{rec}	Reverse Recovery Energy		T _J = 25℃		1.5		mJ
⊏rec	Reverse Recovery Energy	X	T _J = 125℃		3.9		ШJ
$R_{ extsf{ heta}JC}$	Diode Thermal Resistance: Junction-To-Case				0.34		°C/W

IGBT, Brake-Chopper

Maximum Rated Values (T_C=25°C Unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
	c Continuous Collector Current	T _C = 80℃,	50	А
Ic	Continuous Collector Current	T _C = 25℃	100	А
I _{CM}	Peak Collector Current Repetitive	T _J = 175℃	100	А
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per IGBT	T _C = 25℃ T _{Jmax} =175℃	390	W



Electrical Characteristics of IGBT (T_C =25 °C Unless otherwise specified)

Static characteristics

Symbol	Description	Conditions		Min	Тур	Max	Unit
$V_{\text{GE}(\text{th})}$	Gate-Emitter Threshold Voltage	I_{C} = 1 mA, V_{CE}	I_{C} = 1 mA, V_{CE} = V_{GE}		4.5	5.0	V
M		$I_{\rm C} = 50 \text{ A},$	T _J = 25℃		1.90	2.20	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage		T _J = 125℃		2.20		V
I _{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0V,$ $V_{CE} = V_{CES}, T$	V _{GE} = 0V, V _{CE} = V _{CES} , T _J = 25℃			1	mA
I _{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20V,$ $V_{CE} = 0V, T_J =$	= 25 °C		K	100	nA
C _{ies}	Input Capacitance	V_{CE} = 25V, V_{GE} = 0V , f =1MHz			6.7		nF
C _{oes}	Output Capacitance				0.38		nF

Switching Characteristics

	enalaetenetiee	-				
+	Turn-on Delay Time		T _J = 25℃		240	20
t _{d(on)}			T _J = 125℃		235	ns
+	Rise Time		T _J = 25℃		75	20
tr			T _J = 125℃		75	ns
+	Turn-off Delay Time		T _J = 25℃		235	20
t _{d(off)}	V _{cc} = 60	V _{CC} = 600V,I _C = 50A,	T _J = 125℃		250	ns
t _f	Fall Time	$V_{CC} = 600V, I_C = 50A,$ $R_G = 15 \Omega, V_{GE} = \pm 15V,$ Inductive Load	T _J = 25℃		165	ns
lf		$T_{J} = 125^{\circ}C$ $T_{J} = 25^{\circ}C$	T _J = 125℃		280	115
	Turn-on Switching Loss		T _J = 25℃		3.72	– mJ
E _{on}	Turn-on Switching Loss		T _J = 125℃		4.48	IIIJ
_	Turn-off Switching Loss		T _J = 25℃		2.25	
E _{off}	Turn-on Switching Loss		T _J = 125℃		3.54	mJ
Qg	Total Gate Charge		T _J = 25℃		260	nC
RBSOA	Reverse Bias Safe Operation Area	I_{C} =100A,V _{CC} =960V,Vp=12 Rg = 15 Ω , V _{GE} =+15V to 0			Trapezoid	
SCSOA	Short Circuit Safe Operation Area	V _{CC} = 600V, V _{GE} = 15V, T _J = 150℃		10		μs
R _{θJC}	GBT Thermal Resistance: Junction-To-Case				0.39	°C/W



Diode, Brake-Chopper Maximum Rated Values (T_C =25°CUnless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	50	А
I _{FM}	Diode Maximum Forward Current	100	А

Electrical Characteristics of FWD (T_C=25 °C Unless otherwise specified)

Symbol	Description	Condition	ns	Min	Тур	Max	Unit
		I _F = 50 A ,	T _J = 25℃		2.00	2.20	V
V _{FM}	Forward Voltage	V _{GE} = 0V	T _J = 125℃		2.00		
	Paak Payaraa Paaayany Currant		T _J = 25℃	7	25		А
Irr	rr Peak Reverse Recovery Current		T _J = 125℃		40		A
	di/dt :	l⊧ = 50A, di/dt =700A/µs,	T _J = 25℃		3.03		
Q _{rr}	Reverse Recovery Charge	V _{rr} = 600V, V _{GE} = -15V	T _J = 125℃		6.08		μC
			T _J = 25℃		1.34		
E _{rec}	Reverse Recovery Energy		T _J = 125℃		2.73		mJ
$R_{ extsf{ heta}JC}$	Diode Thermal Resistance: Junction-To-Case				0.49		°C/W

Diode, Rectifier (T_C=25°CUnless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	T _J =25℃	1800	V
I _{FRMSM}	Maximum RMS Forward Current per Chip	T _J =80℃	100	А
I _{RMSM}	Maximum RMS Current at Rectifier Output	T _J =80℃	150	А
	Surray Current @t =10 mg	T _J =25℃	1200	•
I _{FSM}	Surge Current @t _p =10 ms	T _J =150℃	900	A
l ² t	l²t - value	T J =25 ℃	6700	A ² s
IL		T _J =150℃	3900	AS



Electrical Characteristics of Diode (T_C=25°C Unless otherwise specified)

Symbol	Description	Conditions		Min	Тур	Max	Unit
N		L = 100 A	T J =25 ℃		1.15		V
V _F	/ _F Forward voltage	I _F = 100 A ,	T _J =150℃		1.10		V
I _R	Reverse current	V _R =1200V	T J =25 ℃			1	mA
R _{eJC}	Diode Thermal Resistance: Junction	n-To-Case			0.34		°C/W
Internal NTC-Thermistor Characteristic				1	C		

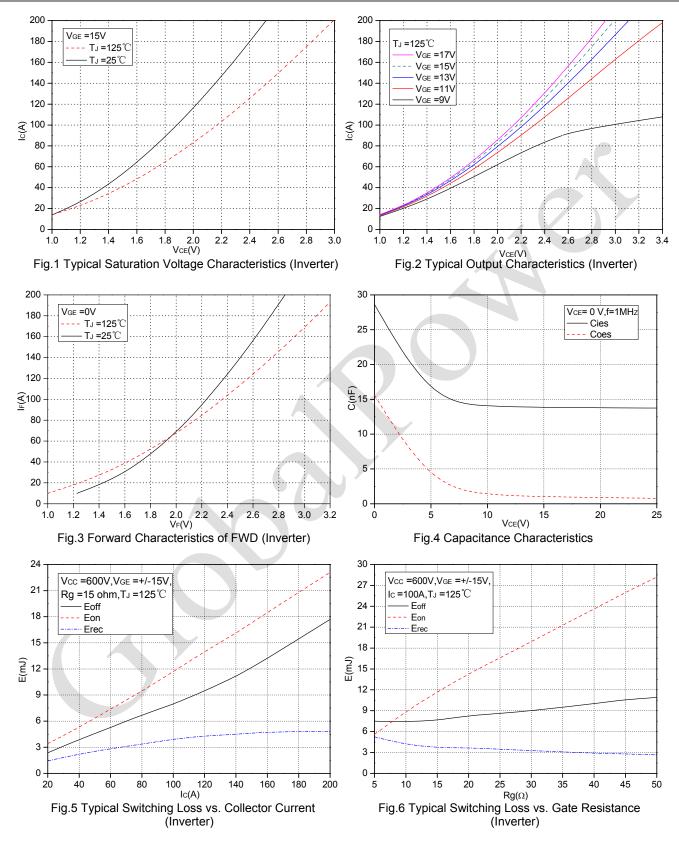
Internal NTC-Thermistor Characteristic

Symbol	Description		Тур	Max	Unit
R ₂₅	T _c =25℃	7	5		kΩ
∆R/R	$T_{C} = 100^{\circ}C, R_{100} = 481\Omega$			±5	%
P ₂₅	T _C =25°C		50		mW
B _{25/50}	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298.15K))]$		3380		к
B _{25/80}	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15K))]$		3440		К

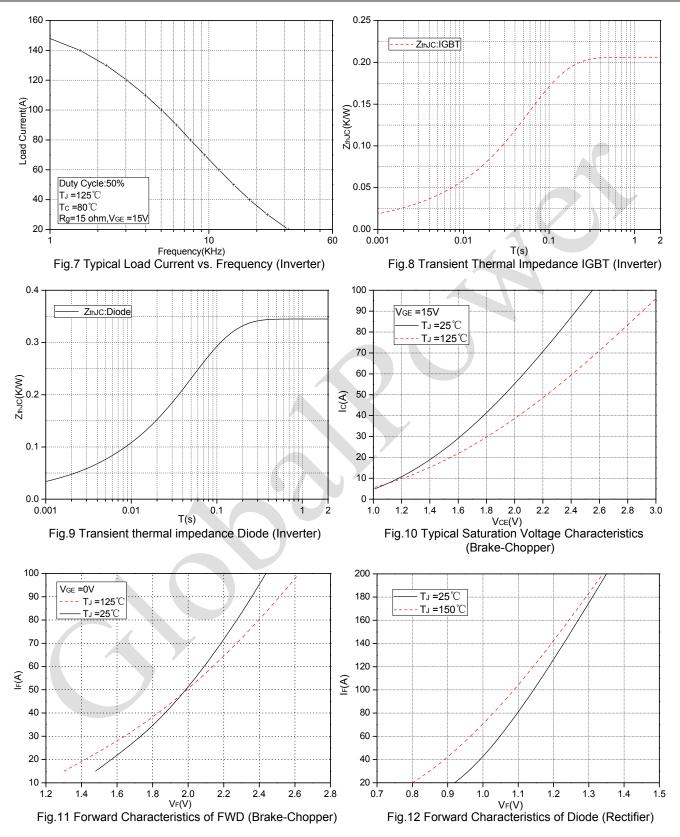
Module

B _{25/80}	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298.15K))]$			3440		K		
Module								
Symbol	Description		Min	Тур	Max	Unit		
V _{iso}	Isolation Voltage(All Terminals Shorted)	f = 50Hz, 1minute			2500	V		
TJ	Maximum Junction Temperature				175	°C		
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	°C		
T _{stg}	Storage Temperature		-40		+125	°C		
R _{0CS}	Case-To-Sink (Conductive Grease Applied)			0.1		°C/W		
т	Mounting Screw:M5		4.0		6.0	N∙m		
G	Weight			300		g		

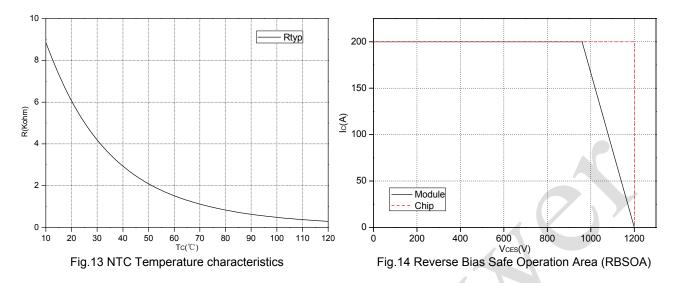






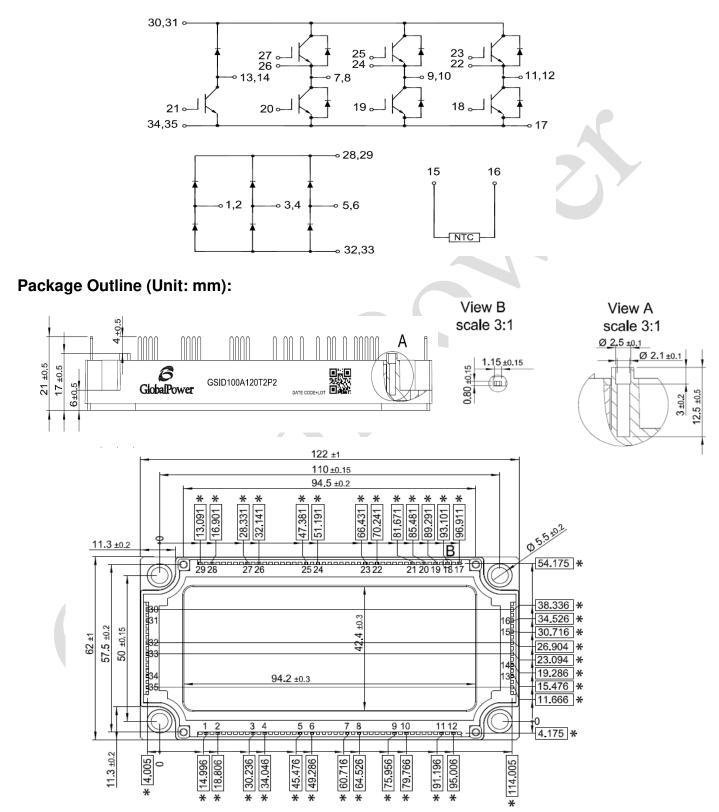








Internal Circuit:





Revision History

Notes

Date	Revision	Notes
4/13/2015	1.0	Initial release

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